Kingbright

3.5x2.8mm SURFACE MOUNT LED LAMP

Part Number: AAA3528SURKCGKS

Hyper Red
Green

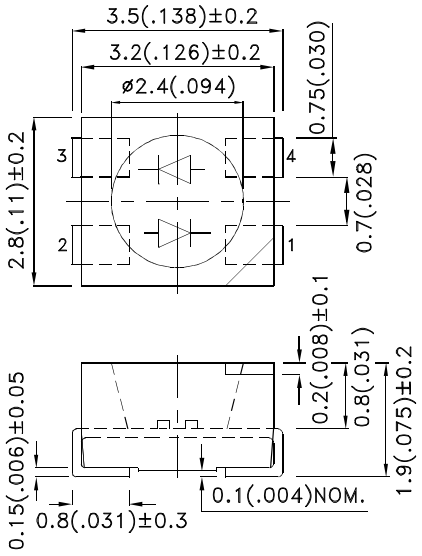
Features

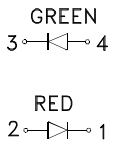
- Both chips can be controlled separately.
- Suitable for all smt assembly and solder process.
- Available on tape and reel.
- Package: 1500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

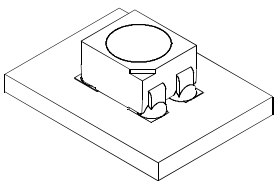
Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.
The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions







Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

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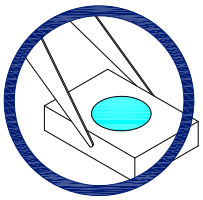
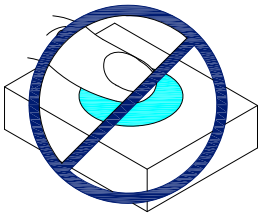
Handling Precautions

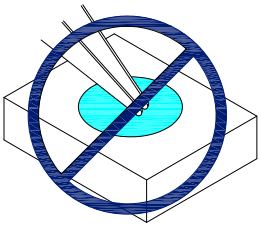
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

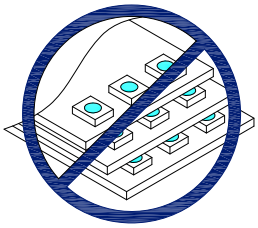


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

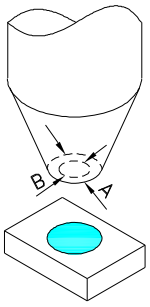




3. Do not stack together assembled PCBs containing exposed LEDs. Impact may scratch the silicone lens or damage the internal circuitry.



4. The outer diameter of the SMD pickup nozzle should not exceed the size of the LED to prevent air leaks. The inner diameter of the nozzle should be as large as possible.
5. A pliable material is suggested for the nozzle tip to avoid scratching or damaging the LED surface during pickup.
6. The dimensions of the component must be accurately programmed in the pick-and-place machine to insure precise pickup and avoid damage during production.



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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
AAA3528SURKCGKS	Hyper Red (AlGaInP)	Water Clear	200	320	120°
	Green (AlGaInP)		40	80	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green	650 574		nm	I_F=20mA
λD [1]	Dominant Wavelength	Hyper Red Green	630 570		nm	I_F=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green	28 20		nm	I_F=20mA
C	Capacitance	Hyper Red Green	35 15		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Hyper Red Green	1.95 2.1	2.5 2.5	V	I_F=20mA
I_R	Reverse Current	Hyper Red Green		10 10	uA	V_R = 5V

Notes:
1.Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Units
Power dissipation	75	75	mW
DC Forward Current	30	30	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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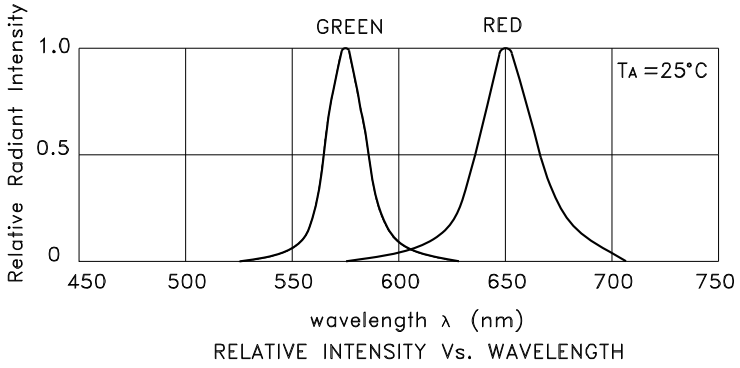
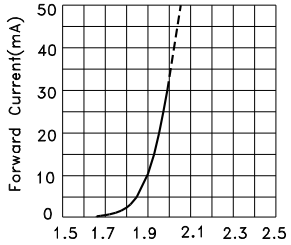
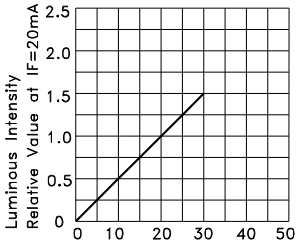


RELATIVE INTENSITY Vs. WAVELENGTH

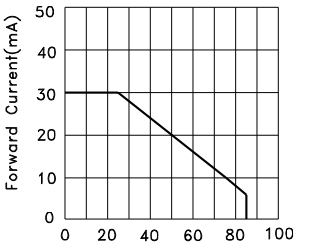
AAA3528SURKCGKS
Hyper Red



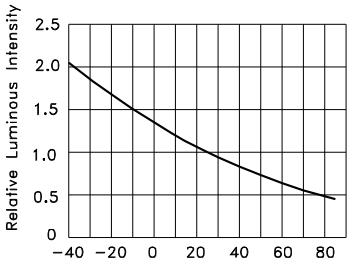
FORWARD CURRENT Vs.
FORWARD VOLTAGE



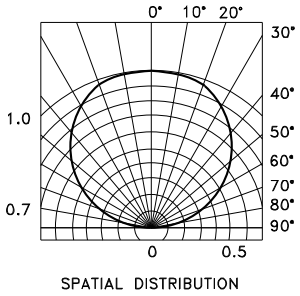
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

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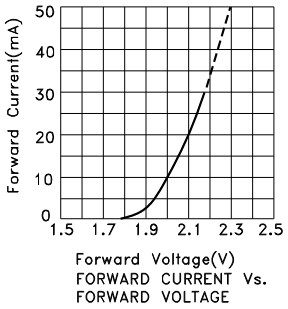
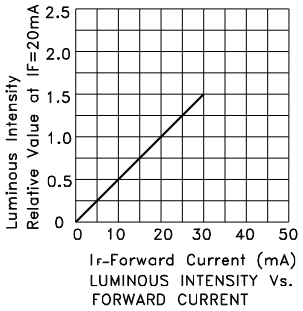
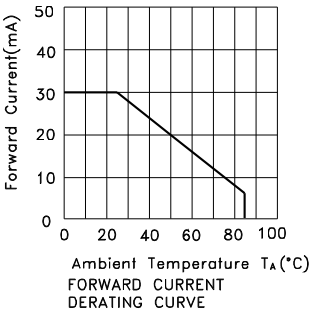
Green



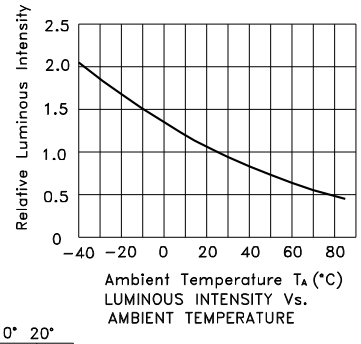
FORWARD CURRENT Vs.
FORWARD VOLTAGE



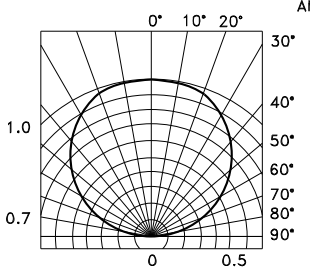
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



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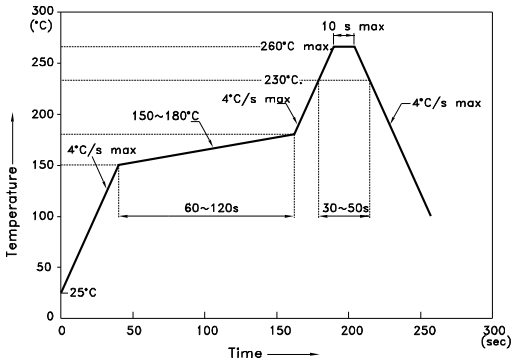
AAA3528SURKCGKS

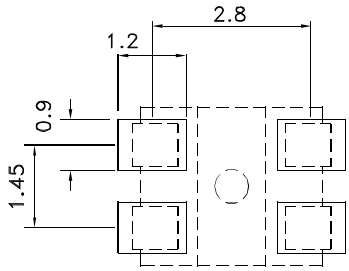
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

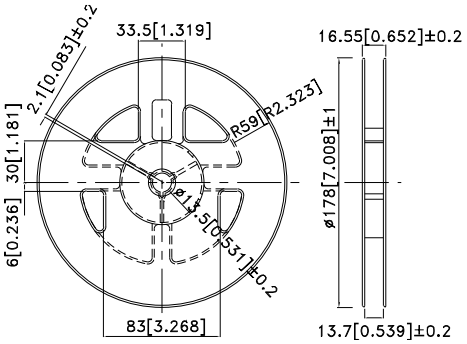


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

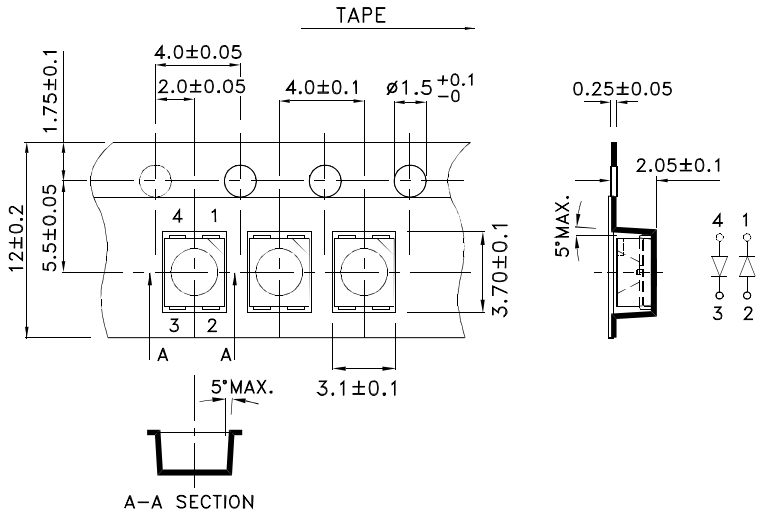
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Dimensions (Units : mm)



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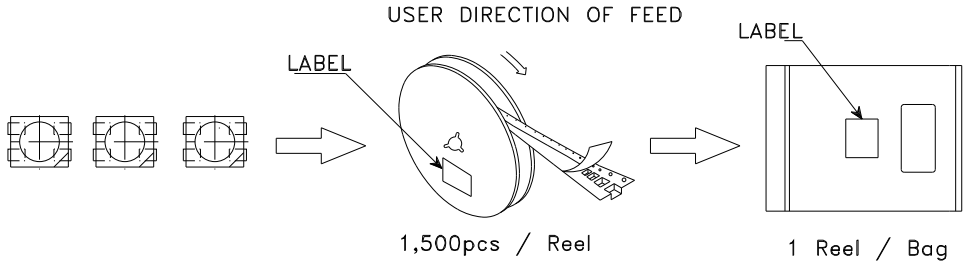
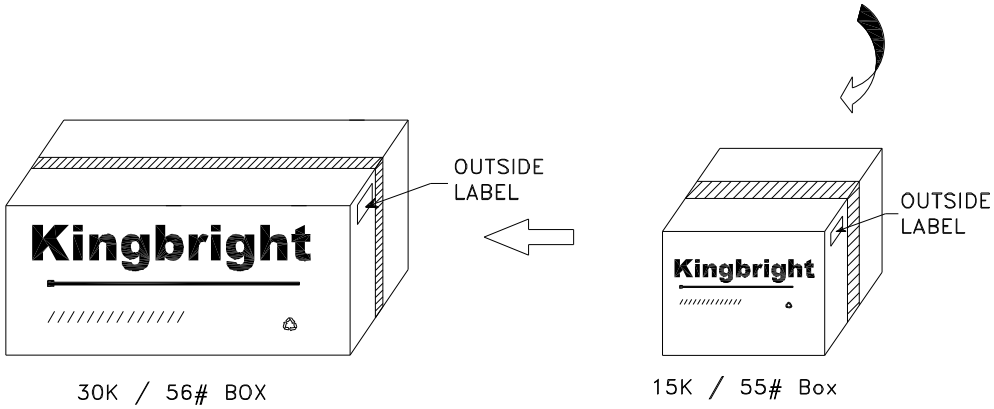
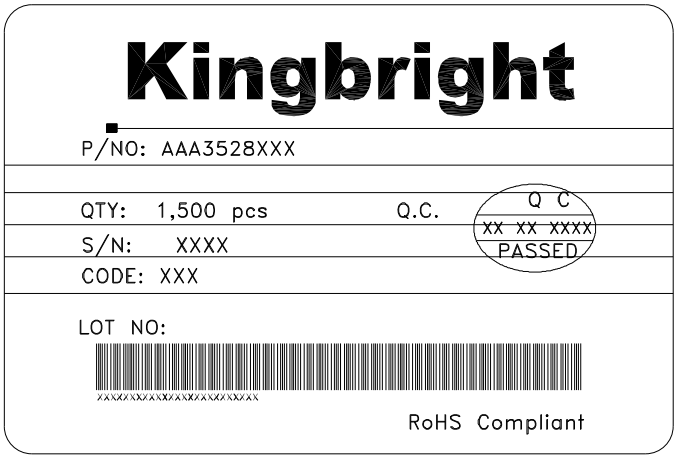
PACKING & LABEL SPECIFICATIONS **AAA3528SURKCGKS**







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